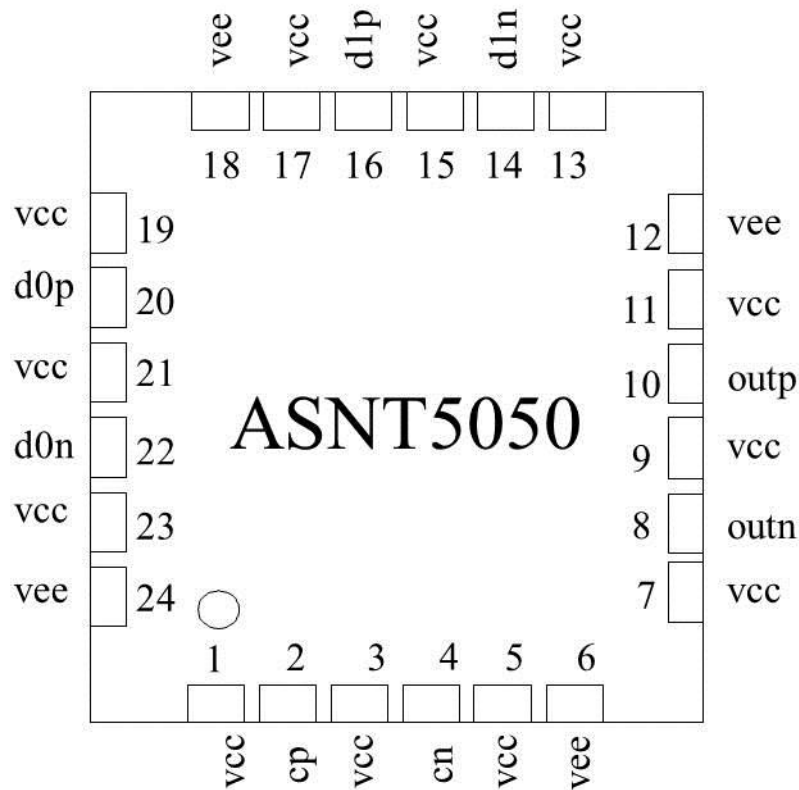




## ASNT5050-PQC DC-32Gbps Broadband Digital 2:1 Multiplexer/Selector

- High speed broadband 2:1 Multiplexer/Selector (MUX)
- Exhibits low jitter and limited temperature variation over industrial temperature range
- Ideal for use as a high isolation selector switch or as a high speed 2-to-1 serializer
- Ideal for high speed proof-of-concept prototyping
- Fully differential CML input interfaces
- Fully differential CML output interface with 400mV single-ended swing
- Single +3.3V or -3.3V power supply
- Power consumption: 450mW
- Fabricated in SiGe for high performance, yield, and reliability
- Standard MLF/QFN 24-pin package



## DESCRIPTION

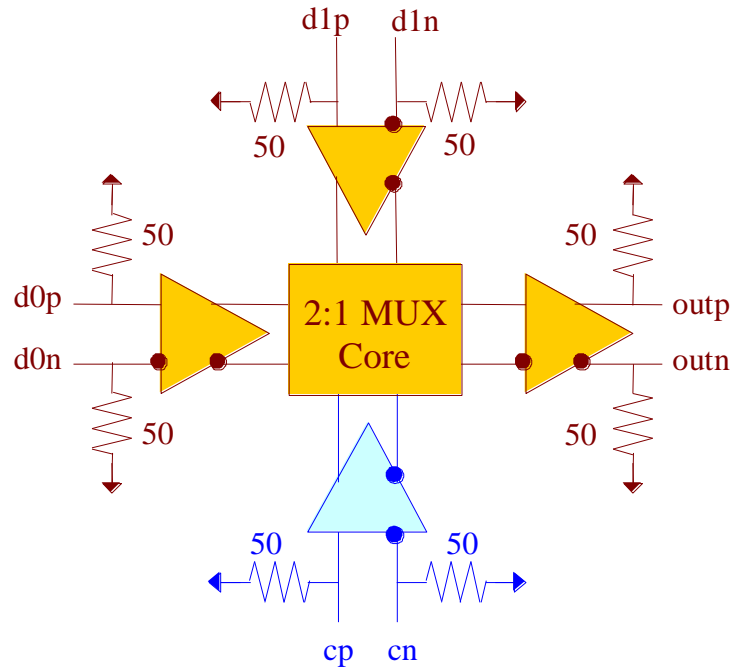


Fig. 1. Functional Block Diagram

The temperature stable ASNT5050-PQC SiGe IC can be utilized as either a high isolation selector switch or a high speed 2:1 serializer, and is intended for use in high-speed measurement / test equipment. When employed as a selector switch, the IC shown in Fig. 1 can route one of its differential data input signals d0p/d0n or d1p/d1n to its differential output outp/outn while effectively blocking the other data input. Selection of a specific data input is achieved through appropriate external DC biasing of the selector signal inputs cp/cn. As a 2:1 serializer, the IC can receive a high speed input data signal into d0p/d0n and d1p/d1n and effectively multiplex them into a double frequency rate NRZ output data signal to its differential output outp/outn by using a high speed input clock signal on its selector signal inputs cp/cn.

The part's I/O's support the CML logic interface with on chip 50 $\Omega$  termination to vcc and may be used differentially, AC/DC coupled, single-ended, or in any combination (see also POWER SUPPLY CONFIGURATION). In the DC-coupling mode, the input signal's common mode voltage should comply with the specifications shown in ELECTRICAL CHARACTERISTICS. In the AC-coupling mode, the input termination provides the required common mode voltage automatically. The differential DC signaling mode is recommended for optimal performance.

## POWER SUPPLY CONFIGURATION

The part can operate with either negative supply (vcc = 0.0V = ground and vee = -3.3V), or positive supply (vcc = +3.3V and vee = 0.0V = ground). In case of the positive supply, all I/Os need AC termination when connected to any devices with 50 $\Omega$  termination to ground. Different PCB layouts will be needed for each different power supply combination.



All the characteristics detailed below assume  $V_{CC} = 0.0V$  and  $V_{EE} = -3.3V$ .

## ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground.

Table 1. Absolute Maximum Ratings

Parameter	Min	Max	Units
Supply Voltage ( $V_{EE}$ )		-3.6	V
Power Consumption		0.50	W
RF Input Voltage Swing (SE)		1.0	V
Case Temperature		+90	$^{\circ}C$
Storage Temperature	-40	+100	$^{\circ}C$
Operational Humidity	10	98	%
Storage Humidity	10	98	%

## TERMINAL FUNCTIONS

TERMINAL			DESCRIPTION
Name	No.	Type	
<b>High-Speed I/Os</b>			
d0p	20	CML input	Differential data input signals with internal SE 50 $\Omega$ termination to $V_{CC}$ .
d0n	22		
d1p	16	CML input	Differential data input signals with internal SE 50 $\Omega$ termination to $V_{CC}$ .
d1n	14		
cp	2	CML input	Differential clock input signals with internal SE 50 $\Omega$ termination to $V_{CC}$ .
cn	4		
outp	10	CML output	Differential data output signals with internal SE 50 $\Omega$ termination to $V_{CC}$ . Also require external SE 50 $\Omega$ termination to $V_{CC}$ .
outn	8		
<b>Supply and Termination Voltages</b>			
Name	Description		Pin Number
vcc	Positive power supply. (+3.3V or 0)		1, 3, 5, 7, 9, 11, 13, 15, 17, 19, 21, 23
vee	Negative power supply. (0V or -3.3V)		6, 12, 18, 24



## ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
<b>General Parameters</b>					
vee	-3.1	-3.3	-3.5	V	±6%
vcc		0.0		V	External ground
I <sub>vee</sub>		135		mA	
Power consumption		450		mW	
Junction temperature	-40	25	125	°C	
<b>HS Input Data (d0p/d0n) (d1p/d1n)</b>					
Data rate / Frequency	DC		32/16	Gbps/GHz	When used as a selector
Data rate	DC		16	Gbps	When used as a multiplexer
Swing	0.05		1.0	V	Differential or SE, p-p
CM Voltage Level	vcc-0.8		vcc	V	Must match for both inputs
<b>HS Input Clock (cp/cn)</b>					
Frequency	DC		16	GHz	
Swing	0.05		1.0	V	Differential or SE, p-p
CM Voltage Level	vcc-0.8		vcc	V	Must match for both inputs
Duty cycle	45	50	55	%	
<b>HS Output Data (outp/outn)</b>					
Data rate / Frequency	DC		32/16	Gbps/GHz	When used as a selector
Data rate	DC		32	Gbps	When used as a multiplexer
Logic "1" level		vcc		V	
Logic "0" level		vcc-0.4		V	With external 50Ωm DC termination
Rise/Fall times	12	13	14	ps	20%-80%
Output Jitter			2	ps	Peak-to-peak

## PACKAGE INFORMATION

The chip die is housed in a standard 24-pin QFN package shown in Fig. 2. It is recommended that the center heat slug located on the back side of the package is soldered to the vee plain that is ground for the positive supply or power for the negative supply.

The part's identification label is ASNT5050-PQC. The first 8 characters of the name before the dash identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the dash represent the package's manufacturer, type, and pin out count.

This device complies with the Restriction of Hazardous Substances (RoHS) per EU 2002/95/EC for all six substances.

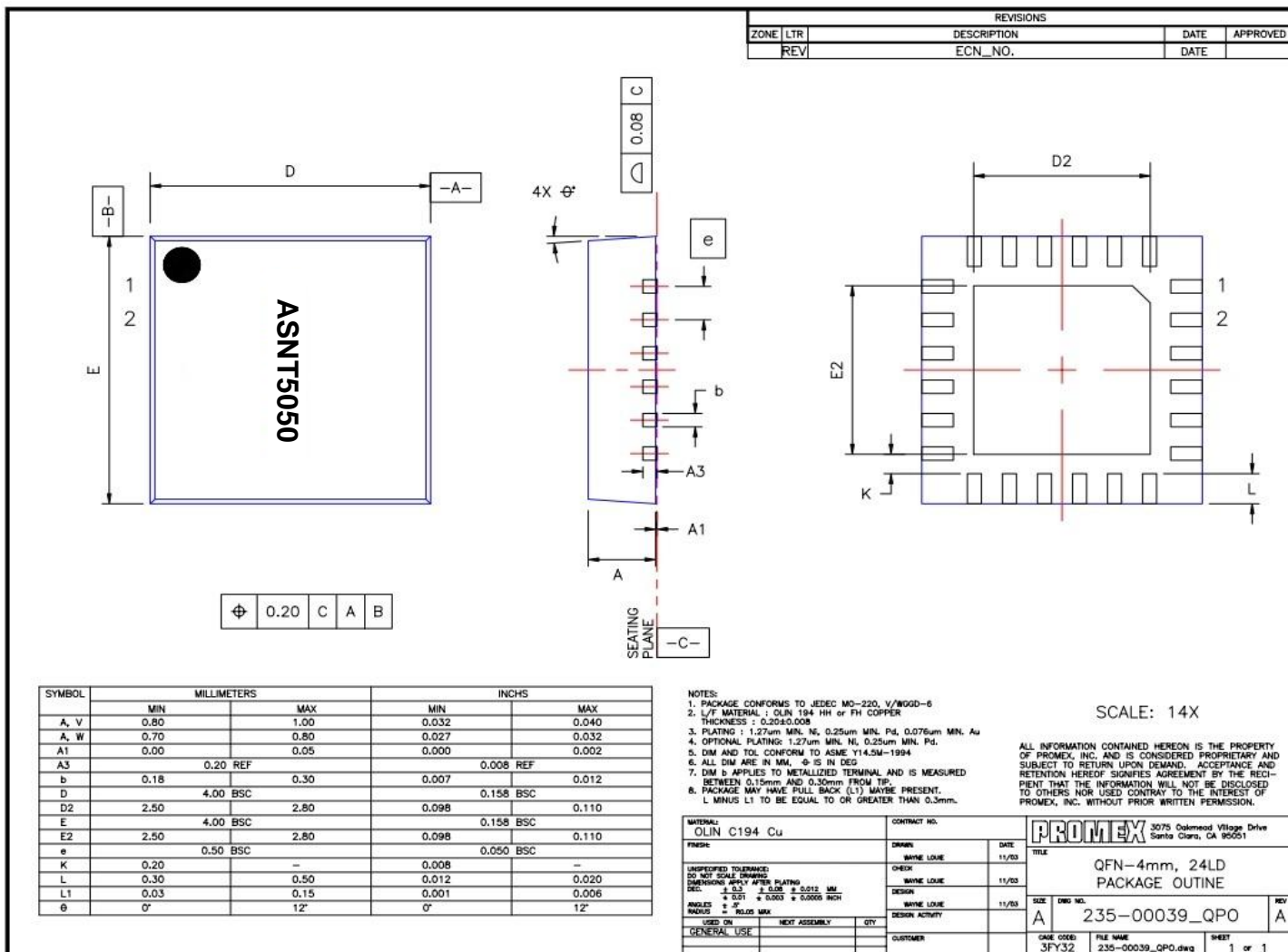


Fig. 2. QFN 24-Pin Package Drawing (All Dimensions in mm)



## REVISION HISTORY

Revision	Date	Changes
4.0.1	01-2013	Revised title Revised pinout drawing Revised functional block diagram Revised description Revised terminal functions Revised electrical characteristics Revised package information Format correction
3.0	01-2012	Added power supply configuration text Added absolute maximums rating table Revised electrical characteristics section Revised package information section Added mechanical drawing
2.0	02-2009	Revised electrical characteristics section Revised package information section
1.0	01-2009	First release